

Title (en)  
HYPEREUTECTIC ALUMINUM/SILICON ALLOY DIE-CAST MEMBER AND PROCESS FOR PRODUCING SAME

Title (de)  
DRUCKGUSSELEMENT AUS HYPEREUTEKTISCHER ALUMINIUM/SILIZIUMLEGIERUNG UND VERFAHREN ZUR HERSTELLUNG DAVON

Title (fr)  
ÉLÉMENT MOULÉ SOUS PRESSION EN ALLIAGE HYPEREUTECTIQUE À BASE D'ALUMINIUM ET DE SILICIUM ET PROCÉDÉ PERMETTANT DE PRODUIRE CE DERNIER

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Application  
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Abstract (en)  
The present invention provides a hypereutectic aluminum-silicon alloy die-cast member which contains 20.0% by mass to 30.0% by mass of silicon and also has a thickness of 2.5 mm or less, and a method for producing the same. Disclosed is a die-cast member made of a hypereutectic aluminum-silicon alloy containing 20.0% by mass to 30.0% by mass of silicon, wherein the die-cast member has a thickness of 2.5 mm or less and an average size of primary crystal Si is 0.04 mm to 0.20 mm.

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